

# Ramani Mayappan

## List of Publications by Year in descending order

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30  
papers

260  
citations

1307366

7  
h-index

996849

15  
g-index

30  
all docs

30  
docs citations

30  
times ranked

153  
citing authors

#	ARTICLE	IF	CITATIONS
1	Effect of Bi addition on the activation energy for the growth of Cu <sub>5</sub> Zn <sub>8</sub> intermetallic in the Sn-Cu lead-free solder. <i>Intermetallics</i> , 2010, 18, 730-735.	1.8	88
2	The effect of crosshead speed on the joint strength between Sn-Zn-Bi lead-free solders and Cu substrate. <i>Journal of Alloys and Compounds</i> , 2007, 436, 112-117.	2.8	35
3	The effect of adding Zn into the Sn-Ag-Cu solder on the intermetallic growth rate. <i>Journal of Materials Science: Materials in Electronics</i> , 2014, 25, 2913-2922.	1.1	30
4	Effect of sample perimeter and temperature on Sn-Cu based lead-free solders. <i>Materials Letters</i> , 2006, 60, 2383-2389.	1.3	18
5	Phase development in La <sub>2</sub> O <sub>3</sub> doped Al <sub>2</sub> O <sub>3</sub> :TiO <sub>2</sub> ceramic membranes. <i>Journal of the European Ceramic Society</i> , 1999, 19, 1847-1857.	2.8	15
6	Wetting and Intermetallic Study between Sn-3.5Ag-1.0Cu-xZn Lead-Free Solders and Copper Substrate (x) Tj ETQq0,0,0 rgBT /Overlock 11	0.3	11
7	Growth of Cu-Zn <sub>5</sub> and Cu <sub>5</sub> Zn <sub>8</sub> Intermetallic Compounds in the Sn-9Zn/Cu Joint during Liquid State Aging. <i>Advanced Materials Research</i> , 0, 173, 90-95.	0.3	10
8	Improvement in Intermetallic Thickness and Joint Strength in Carbon Nanotube Composite Sn-3.5Ag Lead-free Solder. <i>Materials Today: Proceedings</i> , 2016, 3, 1338-1344.	0.9	10
9	Activation energy for Cu-Sn intermetallic in CNT-reinforced Sn-1.0Ag-0.5Cu solder. <i>Soldering and Surface Mount Technology</i> , 2019, 32, 65-72.	0.9	9
10	Intermetallic growth activation energy improvement in graphene doped Sn-3.5Ag solder. <i>Materials Letters</i> , 2022, 310, 131480.	1.3	6
11	Morphology and Intermetallics Study of (Sn-8Zn-3Bi)-1Ag Solder under Liquid-State Aging. <i>Advanced Materials Research</i> , 0, 620, 273-277.	0.3	4
12	The effect of graphene on the intermetallic and joint strength of Sn-3.5Ag lead-free solder. <i>AIP Conference Proceedings</i> , 2017, , .	0.3	4
13	Intermetallic Evolution of Sn-3.5Ag-1.0Cu-0.1Zn/Cu Interface under Thermal Aging. <i>Advanced Materials Research</i> , 0, 620, 142-146.	0.3	3
14	Characterization of Sn-3.5Ag-1.0Cu Lead-Free Solder Prepared via Powder Metallurgy Method. <i>Advanced Materials Research</i> , 2012, 501, 160-164.	0.3	3
15	Effects of Recycled-Aluminum Additions on the Mechanical Properties of Sn-0.7Cu/Cu-Substrate Lead-Free Solder Joints. <i>Advanced Materials Research</i> , 0, 795, 446-450.	0.3	3
16	Silver effect on the intermetallic growth in the Sn-8Zn-3Bi lead-free solder. <i>Materials Today: Proceedings</i> , 2018, 5, 17553-17560.	0.9	3
17	Intermetallic Study on the Modified Sn-3.5Ag-1.0Cu-1.0Zn Lead Free Solder. <i>Materials Science Forum</i> , 2016, 857, 3-7.	0.3	2
18	Intermetallic Growth Retardation with the Addition of Graphene in the Sn-3.5Ag Lead-free Solder. <i>IOP Conference Series: Materials Science and Engineering</i> , 2017, 205, 012017.	0.3	2

#	ARTICLE	IF	CITATIONS
19	The effect of Ni addition on Cu-Sn intermetallic growth rate values in the SAC solder. AIP Conference Proceedings, 2018, , .	0.3	2
20	Microstructure Evolution of Sn-3.5Ag-1.0Cu-0.5Ni/Cu System Lead Free Solder under Long Term Thermal Aging. Advanced Materials Research, 0, 620, 263-267.	0.3	1
21	Cu <sub>6</sub> Sn <sub>5</sub> and Cu <sub>3</sub> Sn Intermetallics Study in the Sn-40Pb/Cu System during Long-term Aging. Scientific Research Journal, 2010, 7, 1.	0.4	1
22	Effect of Ag addition on the intermetallic compound and joint strength between Sn-Zn-Bi lead free solder and copper substrate. , 2012, , .		0
23	Intermetallic evolution between Sn-3.5Ag-1.0Cu-xZn lead free solder and copper substrate under long time thermal aging (x: 0, 0.1, 0.4, 0.7). , 2012, , .		0
24	Solder microstructure and intermetallic interface evaluation between Sn-3.5Ag-1.0Cu-xNi lead free solder under long time thermal aging (x: 0, 0.05, 0.2, 0.5). , 2012, , .		0
25	Thermal Properties of Sn-0.7Cu/re-Al Composite Lead-Free Solder. Advanced Materials Research, 2013, 795, 451-454.	0.3	0
26	Morphology and Intermetallic Study of (Sn-8Zn-3Bi)-1Ni Solder under Liquid State Aging. Advanced Materials Research, 0, 1087, 162-166.	0.3	0
27	The effect of Ni addition in SnAgCu solder on microhardness and intermetallic formation. AIP Conference Proceedings, 2018, , .	0.3	0
28	Intermetallic and tensile study of the newly developed Sn-2.0Ag-0.7Cu solder with addition of 0.5 wt.% zinc. AIP Conference Proceedings, 2018, , .	0.3	0
29	The Effect of Zinc Addition on the Characteristics of Sn-2.0Ag-0.7Cu Lead-Free Solders. , 2018, , 767-775.		0
30	Effect of cooling rates on contact angle, joint strength and intermetallic of Sn-9Zn solder alloy. AIP Conference Proceedings, 2021, , .	0.3	0